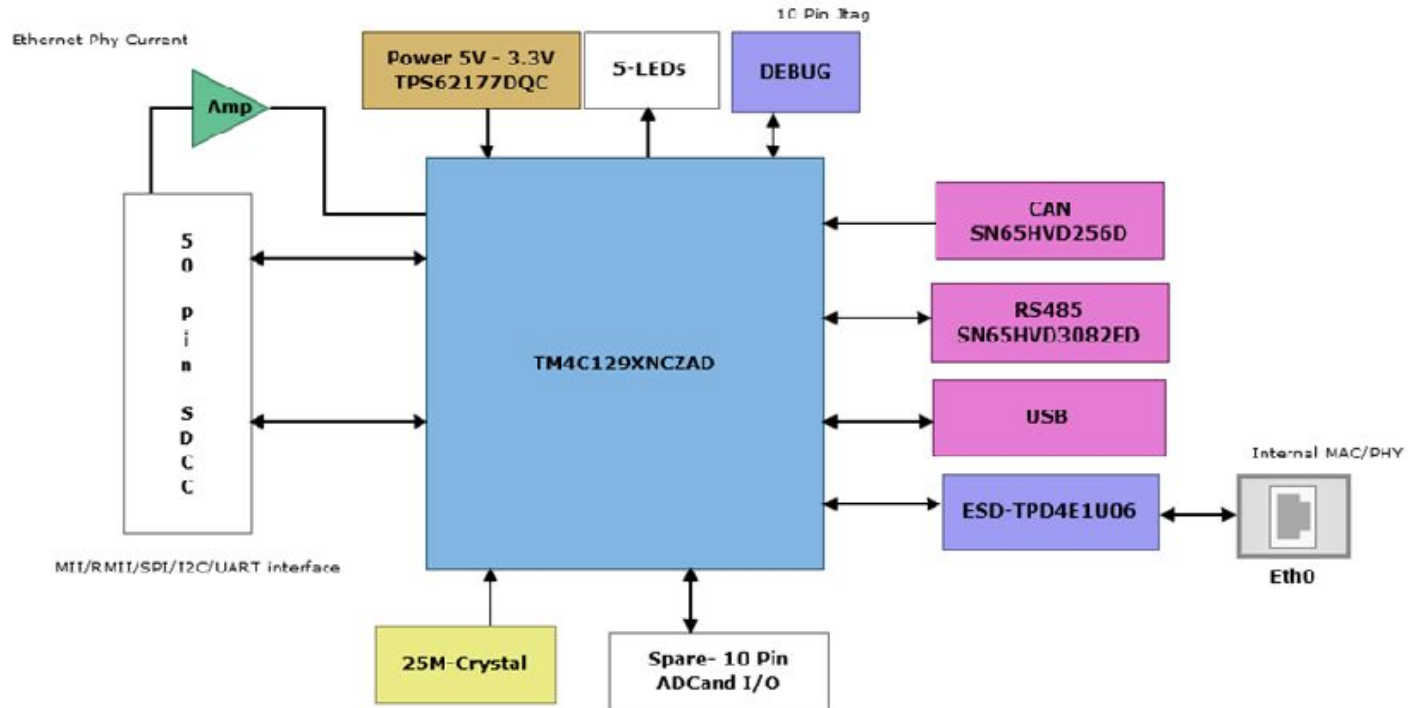


Page 2	BLOCK DIAGRAM
Page 3	MICROCONTROLLER
Page 4	10/100 ETHERNET INTERFACE FOR INTERNAL MAC+PHY, USB
Page 5	CAN+RS485 EXTERNAL INTERFACE, CAN PHY, RS485 PHY
Page 6	MII / RMII INTERFACE, EXTERNAL DC INPUT
Page 7	POWER SUPPLY 3.3V
Page 8	SPARE AND DEBUG
Page 9	MOUNTING HOLES, FIDUCIALS MARKING

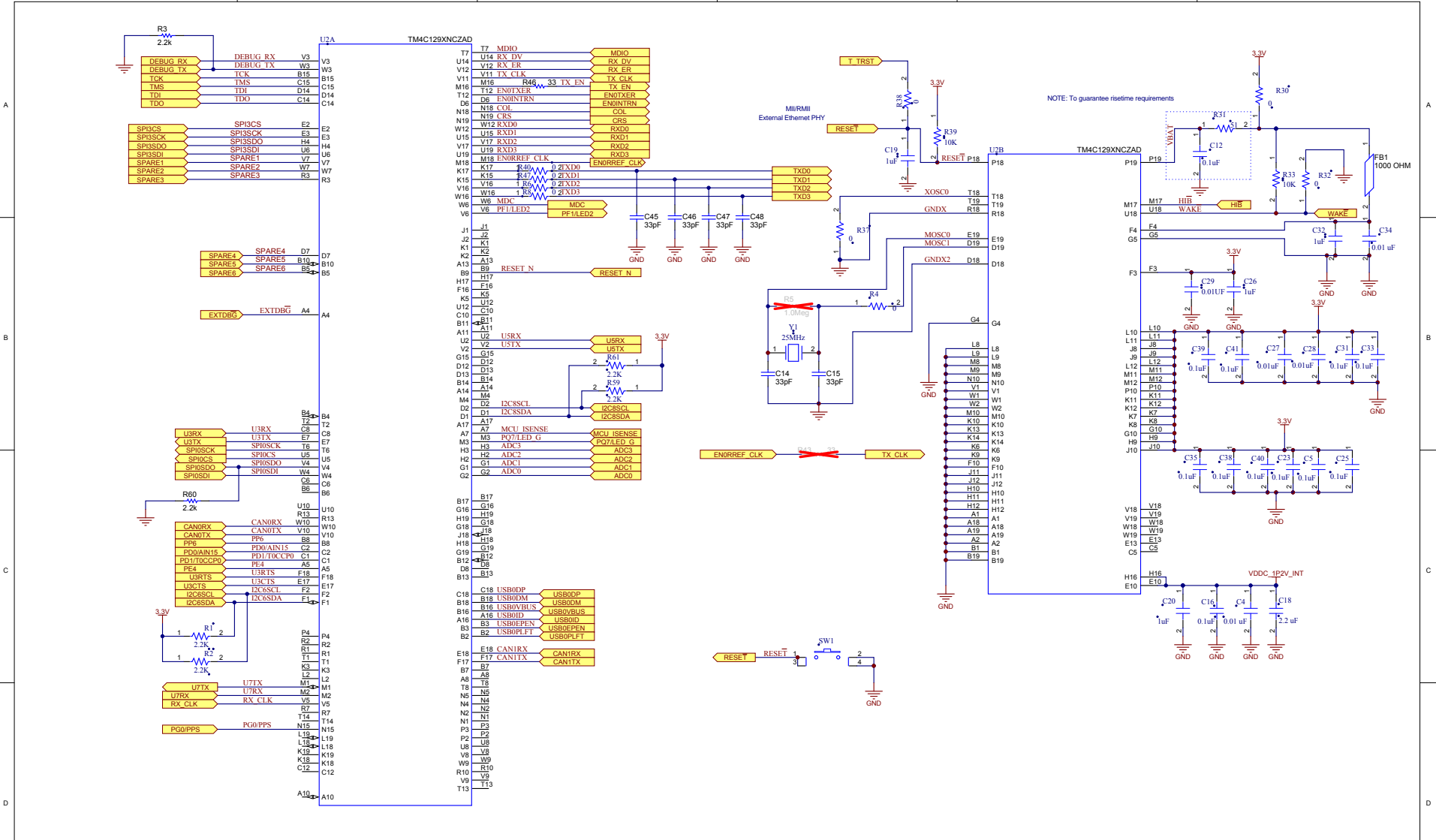
Revision History	
Revision	Notes

Tiva MCU based Gateway



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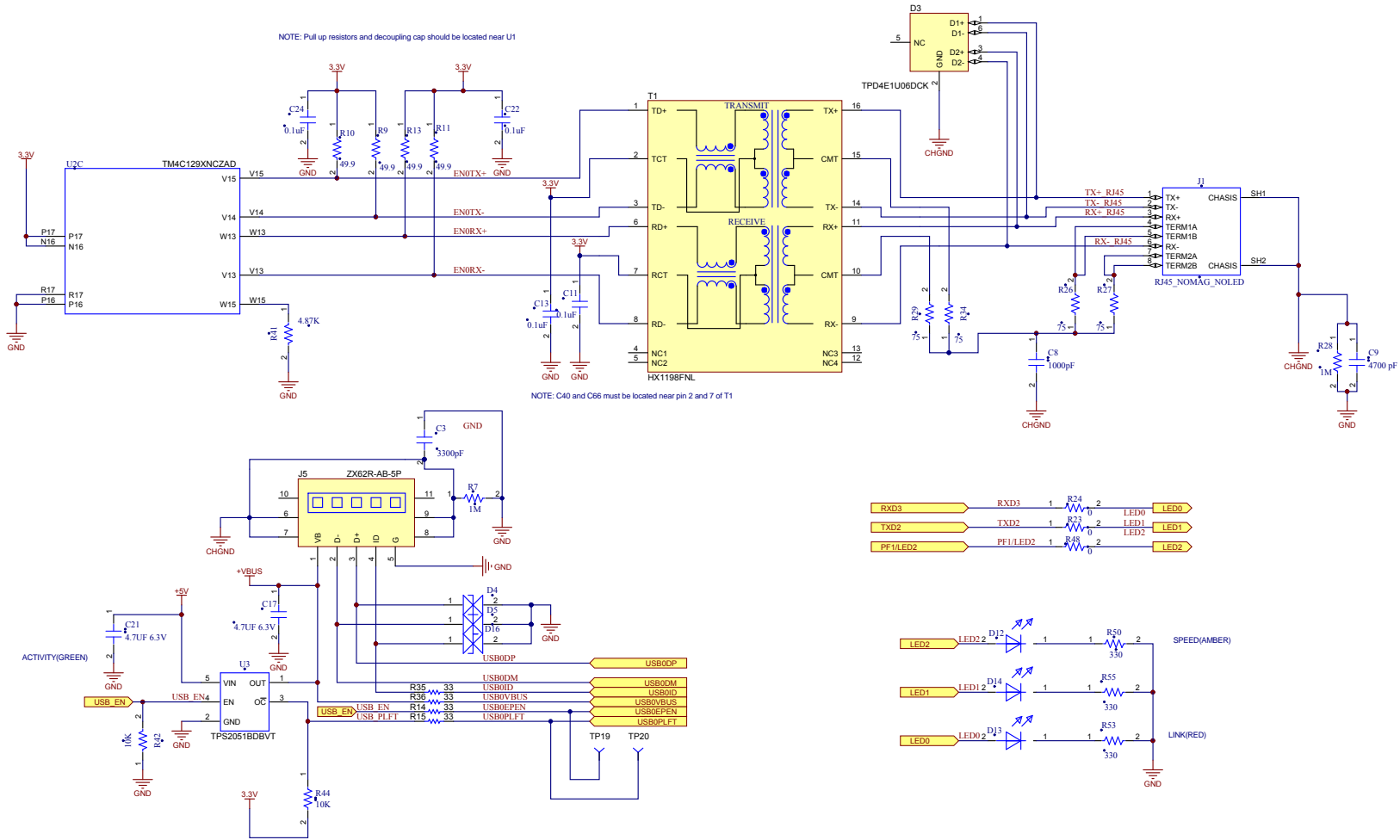
Number: XX###	Rev: E1	Designed for: Public Release	Mod. Date: 2/18/2014
SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00226 (ISE5001)	Sheet Title: BLOCK DIAGRAM
Drawn By:	File: Pcb_Block_Diagram_SchDoc	Sheet: 2 of 9	Size: B
Engineer:	Contact: http://www.ti.com/support		



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SVN Rev.: Not in version control		Project Title: TIDA-00226 (ISE5001)	
Drawn By:		Sheet Title: MICROCONTROLLER	Sheet: 3 of 9
Engineer:		File: Pcb_MICROCONTROLLER_SchDoc	Size: B
		Contact: http://www.ti.com/support	

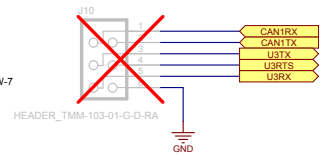
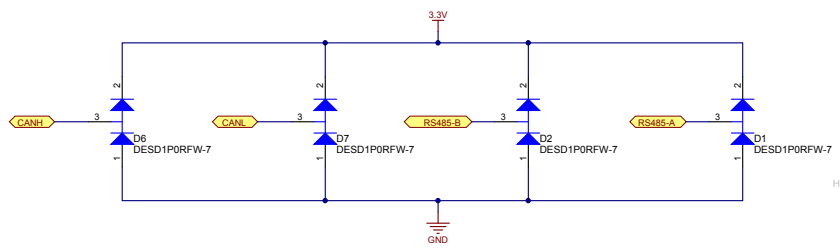
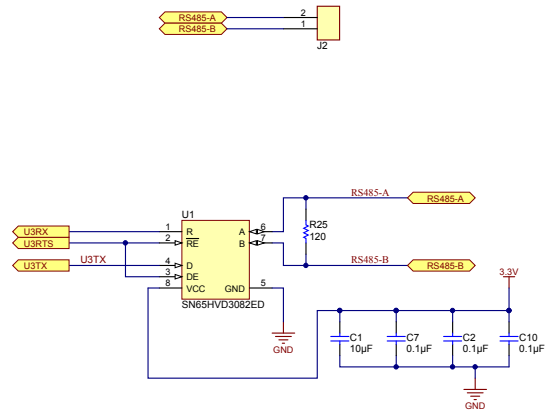
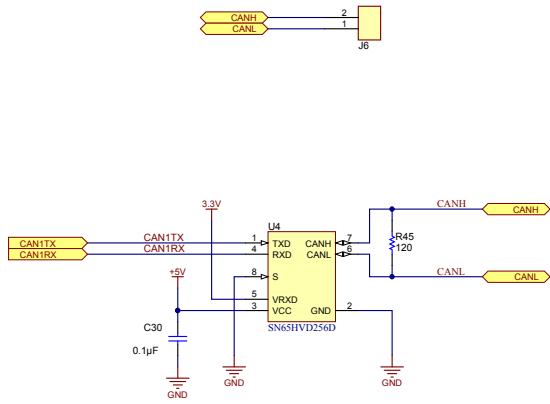


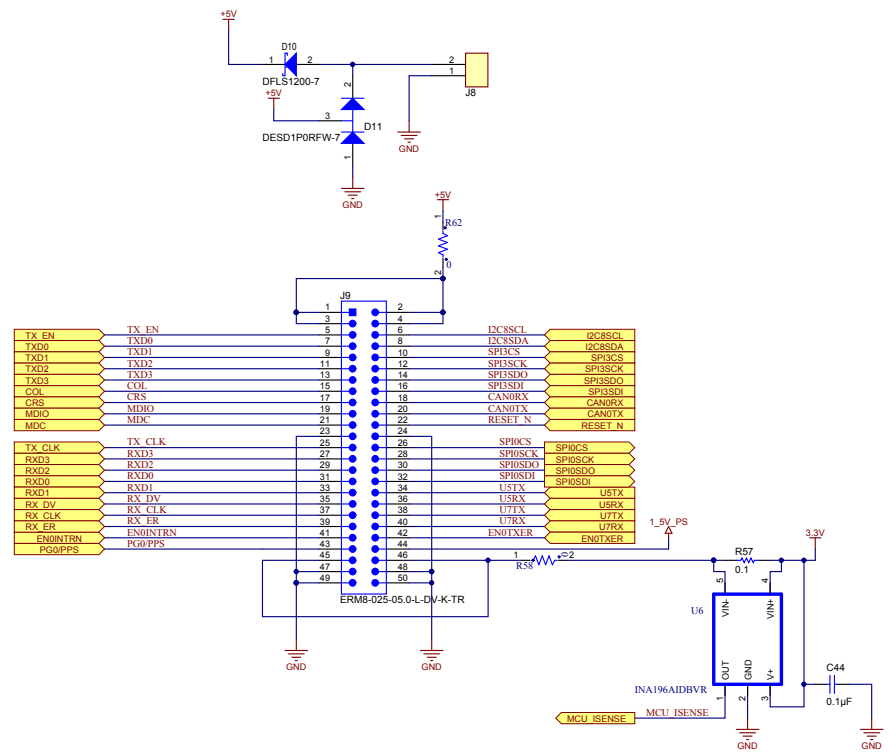
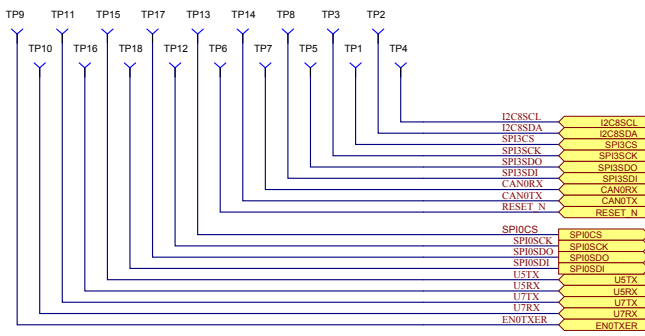


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SVA Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00226 (ISE5001)	
Drawn By:	Engineer:	Sheet Title: 10/100 ETHERNET USB	Sheet: 4 of 9
		File: Pdk_10_100_ETHERNET_USB_SchDoc	Size: B
		Contact: http://www.ti.com/support	



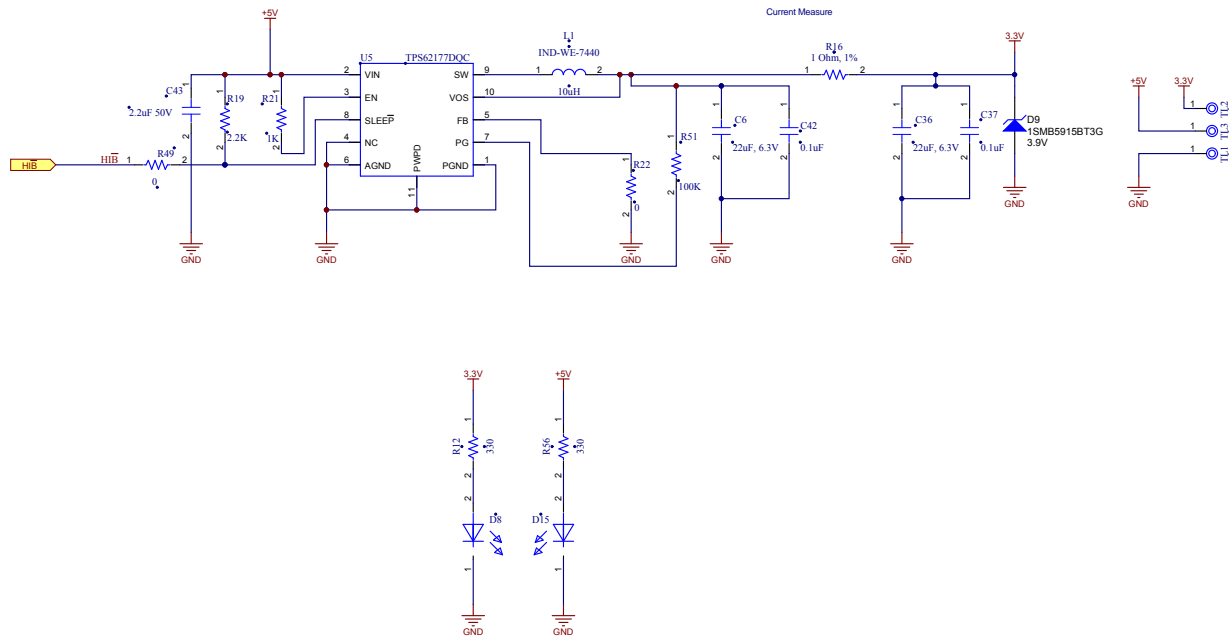




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Number: XX###	Rev: E1	Designed for: Public Release	Mod. Date: 2/18/2014
SVR Rev.: Not in version control		Project Title: TIDA-00226 (ISE5001)	
Drawn By:		Sheet Title: MII / RMII INTERFACE	Sheet 6 of 9
Engineer:		File: Pkg_MII_RMII_INTERFACE_SchDoc	Size: B
		Contact: http://www.ti.com/support	http://www.ti.com



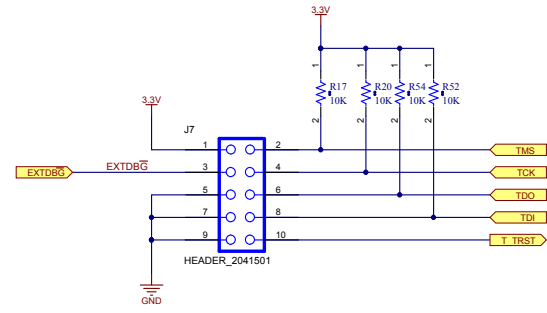
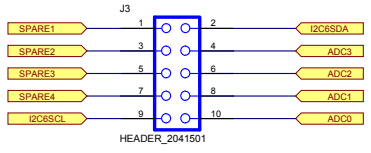


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Designed for: Public Release		Mod. Date: 2/14/2014	
Project Title: TIDA-00226 (ISE5001)			
Number: XX###	Rev: E1	Sheet Title: POWER SUPPLY	
SVN Rev.: Not in version control		Assembly Variant: 001	Sheet: 7 of 9
Drawn By: POWER_SUPPLY_SchDoc		Size: B	
Engineer:		Contact: http://www.ti.com/support	



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Number: XX###	Rev: E1	Designed for: Public Release	Mod. Date: 4/21/2014
SVN Rev.: Not in version control	Assembly Variant: 001	Project Title: TIDA-00226 (ISE5001)	
Drawn By:	File: Pcb_SPARE_AND_DEBUG_SchDoc	Sheet Title: SPARE AND DEBUG	Sheet: 6 of 9
Engineer:	Contact: http://www.ti.com/support		Size: B



H1 NY PMS 440 0025 PH H2 NY PMS 440 0025 PH H5 NY PMS 440 0025 PH H6 NY PMS 440 0025 PH H3 NY PMS 440 0025 PH H4 NY PMS 440 0025 PH

FID5 FID6 FID4 FID3 FID2 FID1

PCB Number: XX####
PCB Rev.

PCB
LOGO
Texas Instruments

You should delete the nylon screws/standoffs and/or the bump-ons as needed for your design (or substitute other parts from Hardware.IntLib). Bump-ons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

LBL1
PCB Label
Size: 0.65" x 0.20"

Z24
Label Assembly Note
This Assembly Note is for PCB labels only

Z23
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

Z21
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z22
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Number: XX####	Rev: E1	Designed for: Public Release	Mod. Date: 2/17/2014
SVN Rev.: Not in version control	Drawn By:	Project Title: TIDA-00226 (ISE5001)	Sheet 9 of 9
Engineer:		Sheet Title: MOUNTING HOLES, FIDUCIALS MARKING	
		Assembly Variant: 001	
		File: Pcb_Hardware_ANSI-B_SchDoc	
		Contact: http://www.ti.com/support	

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